



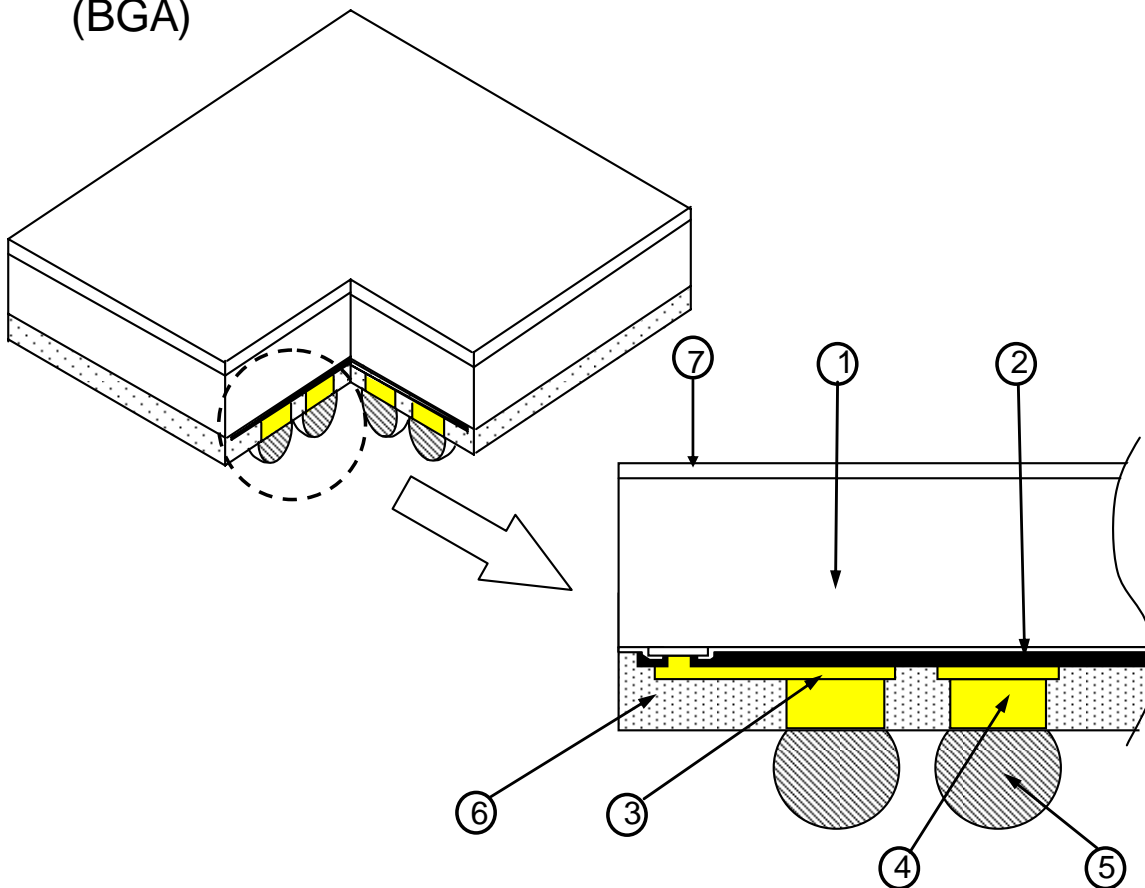
	<h1>Package Standards</h1>		
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## 2. Package Structure (Technical Report : Reference Value)

Package Code : XBGA012-W-1316AEL

Chip material		Si	①
Insulated layer material		Polyimide	②
Reroute material		Cu	③
Terminal land surface material		Cu	④
Outer terminal		Bump/SnAgCu	⑤
Molding	method	Resin molding	⑥
	material	Br/Sb Free Epoxy resin	
Molding	method	Paste-on resin	⑦
	material	Br/Sb Free Epoxy resin	
Mass		3.3 mg	

(BGA)



-	-	<b>Exclusive use for AN30259A</b>
Established	Revised	

Semiconductor Company, Panasonic Corporation

Established: 2008-09-05

Revised : 2009-10-27